Substitute for form 1449A/PTO	Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT *(Use as many sheets as necessary)*	Application Number	10/571,246
	Filing Date	December 5, 2006
	First Named Inventor	Rudhard et al.
	Art Unit	2829
	Examiner Name	Ming Hung HUNG
Sheet 1 of 1	Attorney Docket Number	10191/4346

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No.[1]	Document Number Number - Kind Code[2] (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No.[1]	Foreign Patent Document Country Code[3] - Number[4] - Kind Code[5] (if known)	Publication Date MM-OO-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T[6]

NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No.[1]	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T[2]
		B. TILLACK et al., "Monitoring of Deposition and Dry Etching of Si/SiGe Multiple Stacks", J. Vac. Sci. Technol. B14(1), Jan/Feb 1996, 1996 American Vacuum Society, pp. 102-105.	*
		C.S. PREMACHANDRAN et al., "A Novel Electrically Conductive Wafer Through Hole Filled Vias Interconnect For 3D MEMS Packaging", 2003 Electronic Components and Technology Conference, pp. 627-630.	

Examiner Signature	/Karen Kusumakar/	Date Considered	12/07/2008

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /K.K./